

1 MP, CMOS, Time of Flight, Backside Illumination Sensor

FEATURES

- ▶ 1024 (horizontal) × 1024 (vertical) pixel array
- ▶ 3.5 μm × 3.5 μm square pixels
- ▶ 1/3.6 inch optical format
- ▶ 4-wire SPI or 2-wire I²C serial interface
- ▶ MIPI CSI-2 transmitter interface with support for 1, 2, or 4 data lanes, programmable up to 1.5 Gbps per lane
- ▶ Dual, 3.3 V and 1.27 V external supplies, 1.8 V I/O section
- ▶ Die size: 5.364 mm × 9.799 mm

APPLICATIONS

- ▶ Smartphones
- ▶ Augmented reality (AR)/virtual reality (VR)
- ▶ Machine vision systems (logistics and inventory)
- ▶ Robotics (consumer and industrial)

FUNCTIONAL BLOCK DIAGRAM

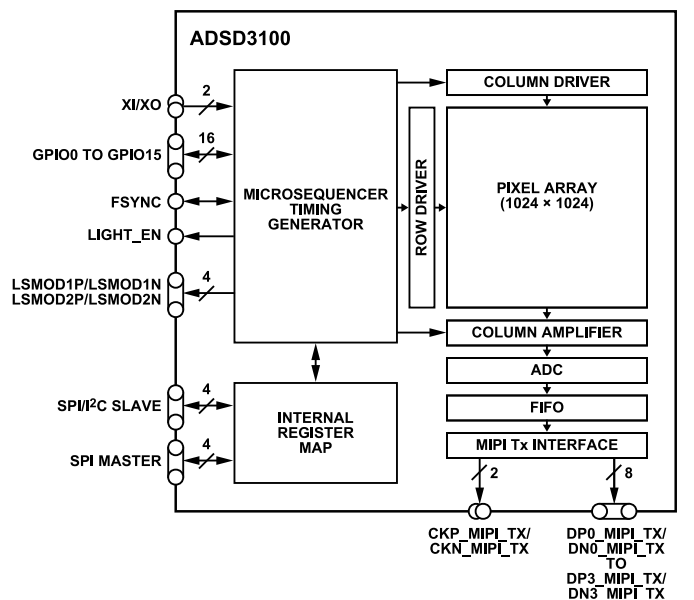


Figure 1.

For more information about the ADS3100, contact Analog Devices, Inc., at sublime3D@analog.com.

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